



Description

The HSCE1218 is the high cell density trench P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

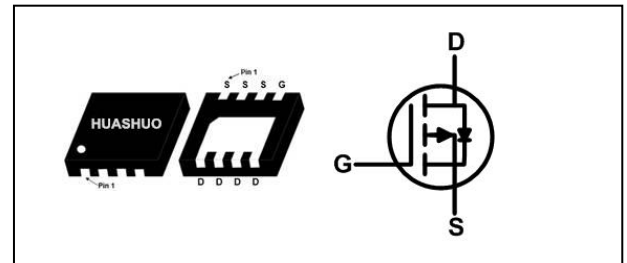
The HSCE1218 meet the RoHS and Green Product requirement with full function reliability approved.

- Super Low Gate Charge
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

Product Summary

| | | |
|-------------------------|-----|----|
| V _{DS} | -12 | V |
| R _{DS(ON),typ} | 3.2 | mΩ |
| I _D | -60 | A |

DFN3.3*3.3 Pin Configuration



Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|-----------------------------------|--|------------|-------|
| V _{DS} | Drain-Source Voltage | -12 | V |
| V _{GS} | Gate-Source Voltage | ± 12 | V |
| I _{D@T_C=25°C} | Continuous Drain Current, V _{GS} @ -4.5V ¹ | -60 | A |
| I _{D@T_C=70°C} | Continuous Drain Current, V _{GS} @ -4.5V ¹ | -32 | A |
| I _{DM} | Pulsed Drain Current ² | -240 | A |
| P _{D@T_C=25°C} | Total Power Dissipation ³ | 83 | W |
| T _{STG} | Storage Temperature Range | -55 to 150 | °C |
| T _J | Operating Junction Temperature Range | -55 to 150 | °C |

Thermal Data

| Symbol | Parameter | Max. | Unit |
|------------------|--|------|------|
| R _{θJA} | Thermal Resistance Junction-Ambient ¹ | 55 | °C/W |
| R _{θJA} | Thermal Resistance Junction-Ambient ¹ (t ≤ 10s) | 20 | °C/W |
| R _{θJC} | Thermal Resistance Junction-Case ¹ | 1.5 | °C/W |



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-------------------------------------|--|--|------|--------|-------|-------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =-250uA | -12 | --- | --- | V |
| ΔBV _{DSS} /ΔT _J | BV _{DSS} Temperature Coefficient | Reference to 25°C, I _D =-1mA | --- | -0.012 | --- | V/°C |
| R _{DS(ON)} | Static Drain-Source On-Resistance ² | V _{GS} =-4.5V, I _D =-20A | --- | 3.2 | 4 | mΩ |
| | | V _{GS} =-2.5V, I _D =-20A | --- | 4.3 | 5.6 | |
| V _{GS(th)} | Gate Threshold Voltage | V _{GS} =V _{DS} , I _D =-250uA | -0.5 | -0.65 | -1.0 | V |
| ΔV _{GS(th)} | V _{GS(th)} Temperature Coefficient | | --- | 2.94 | --- | mV/°C |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} =-12V, V _{GS} =0V, T _J =25°C | --- | --- | -1 | uA |
| I _{GSS} | Gate-Source Leakage Current | V _{GS} = ± 12V, V _{DS} =0V | --- | --- | ± 100 | nA |
| R _g | Gate Resistance | V _{DS} =-0V, V _{GS} =0V, f=1MHz | --- | 7.3 | --- | Ω |
| Q _g | Total Gate Charge (-4.5V) | V _{DS} =-6V, V _{GS} =-4.5V, I _D =-20A | --- | 41 | --- | nC |
| Q _{gs} | Gate-Source Charge | | --- | 10 | --- | |
| Q _{gd} | Gate-Drain Charge | | --- | 14 | --- | |
| T _{d(on)} | Turn-On Delay Time | V _{DD} =-6V, V _{GS} =-4.5V, R _G =3.3Ω, I _D =-20A | --- | 12 | --- | ns |
| T _r | Rise Time | | --- | 7 | --- | |
| T _{d(off)} | Turn-Off Delay Time | | --- | 216 | --- | |
| T _f | Fall Time | | --- | 96 | --- | |
| C _{iss} | Input Capacitance | V _{DS} =-6V, V _{GS} =0V, f=1MHz | --- | 6910 | --- | pF |
| C _{oss} | Output Capacitance | | --- | 1420 | --- | |
| C _{rss} | Reverse Transfer Capacitance | | --- | 1130 | --- | |

Diode Characteristics

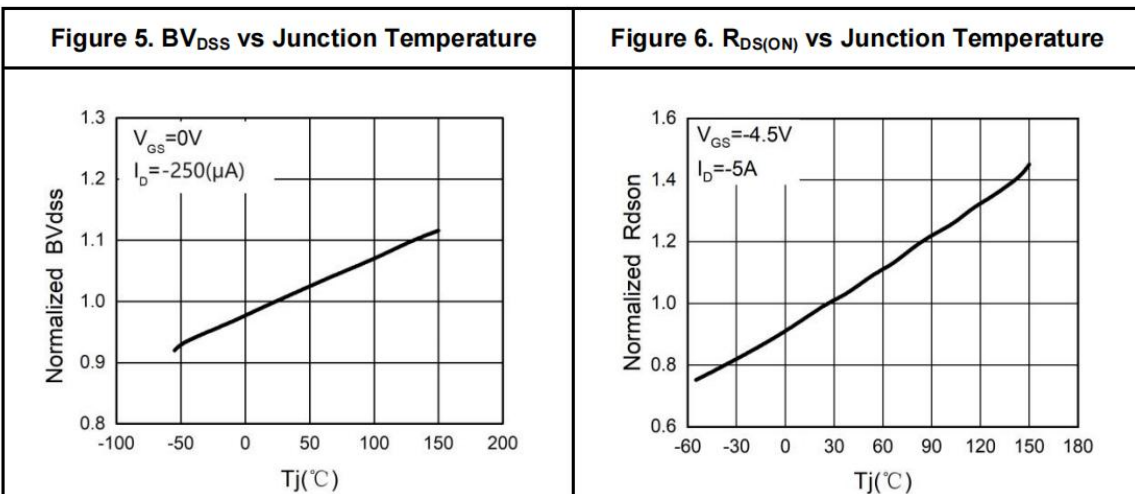
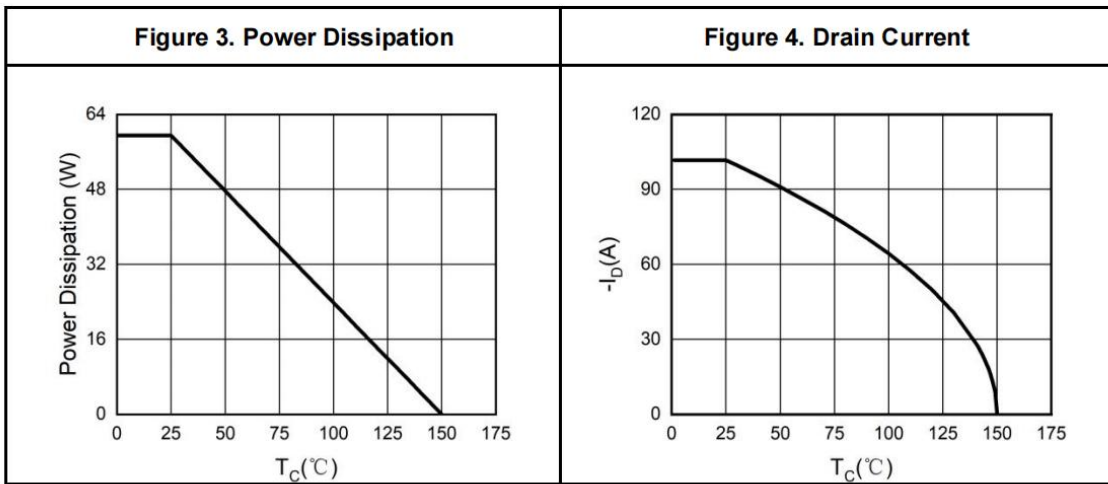
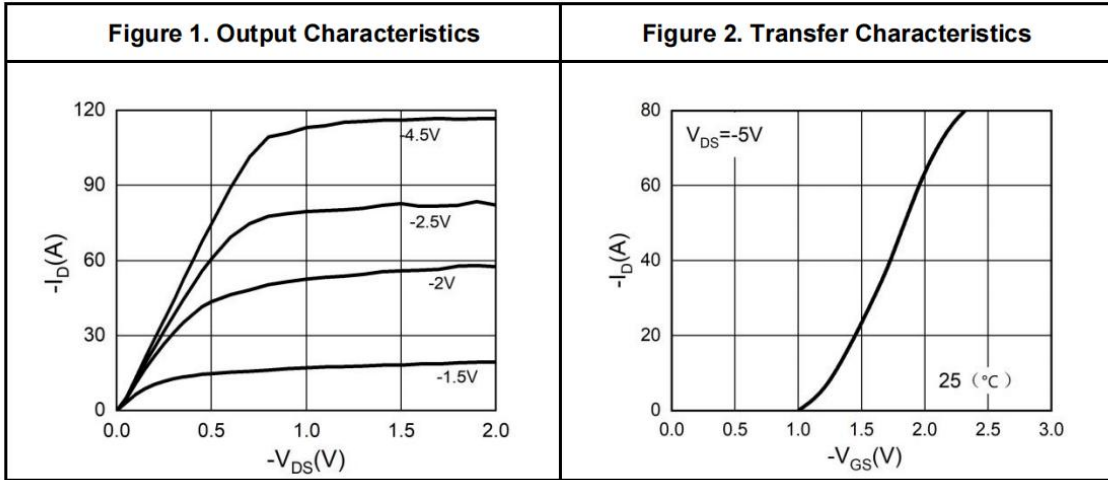
| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-----------------|--|--|------|------|------|------|
| I _S | Continuous Source Current ^{1,4} | V _G =V _D =0V, Force Current | --- | --- | -60 | A |
| V _{SD} | Diode Forward Voltage ² | V _{GS} =0V, I _S =-1A, T _J =25°C | --- | --- | -1.2 | V |
| t _{rr} | Reverse Recovery Time | I _F =-20A, dI/dt=100A/μs, | --- | 25 | --- | nS |
| Q _{rr} | Reverse Recovery Charge | T _J =25°C | --- | 11 | --- | nC |

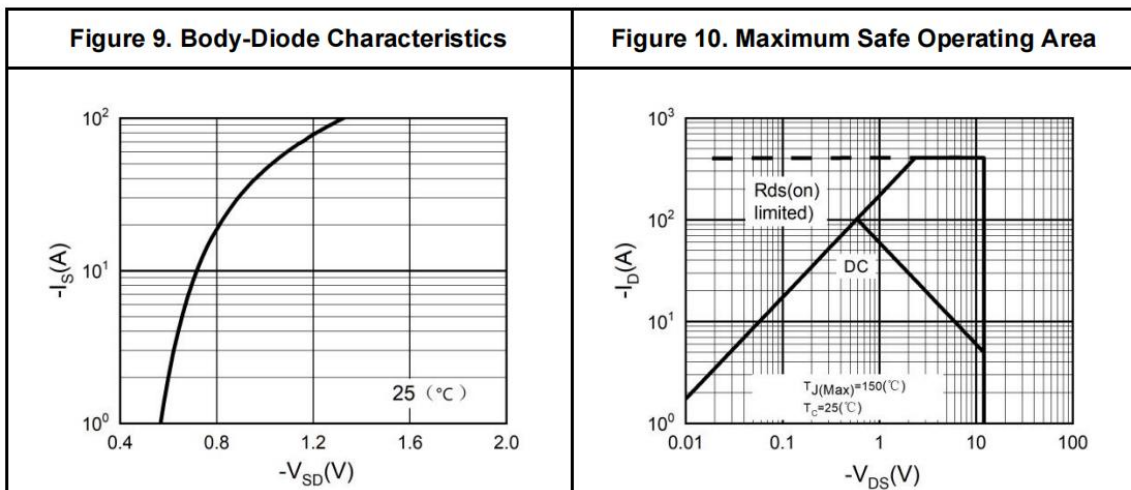
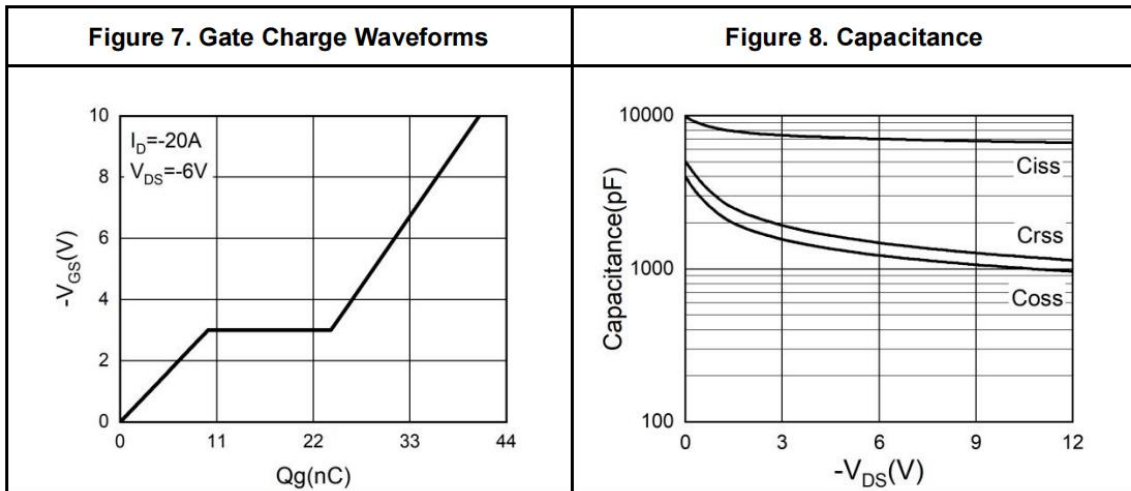
Note :

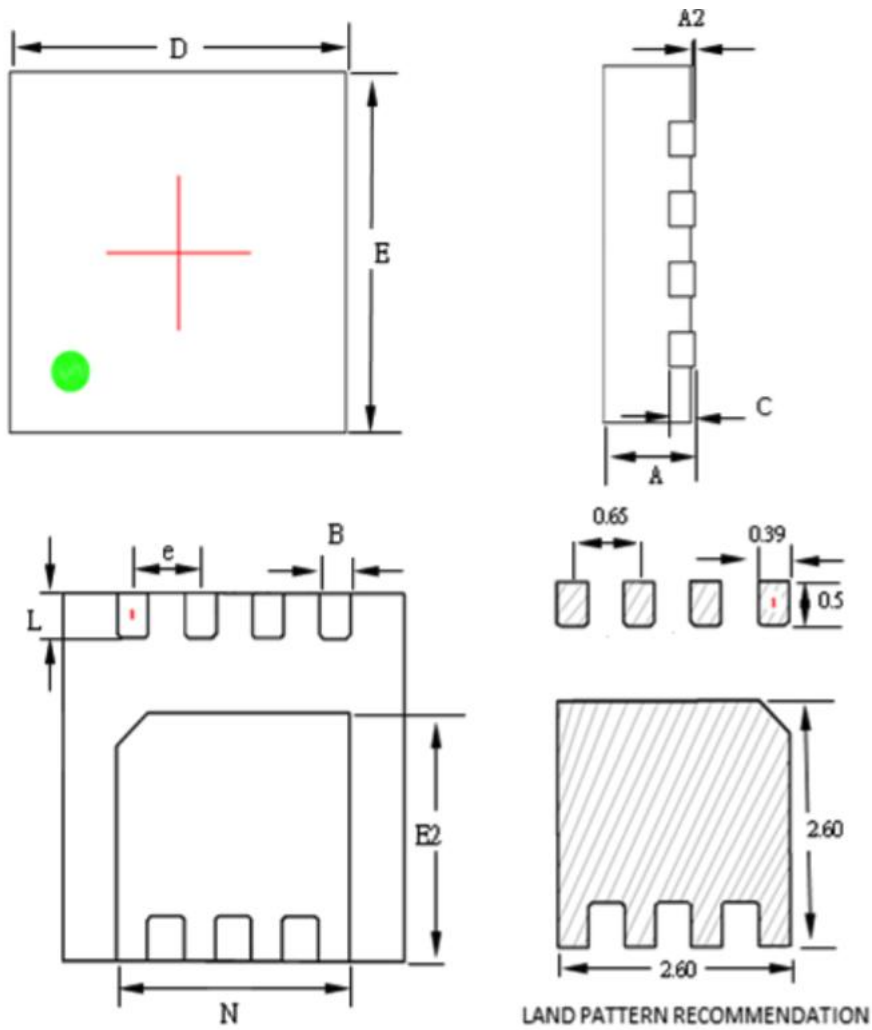
- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
- 3.The power dissipation is limited by 150°C junction temperature
- 4.The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.



Typical Characteristics







| SYMBOLS | MILLIMETERS | | | INCHES | | |
|---------|-------------|------|------|--------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 0.70 | 0.75 | 0.80 | 0.028 | 0.030 | 0.031 |
| A2 | 0.00 | -- | 0.05 | 0.000 | -- | 0.002 |
| B | 0.24 | 0.30 | 0.35 | 0.009 | 0.012 | 0.014 |
| C | 0.10 | 0.15 | 0.25 | 0.004 | 0.006 | 0.010 |
| D | 3.15 | 3.30 | 3.40 | 0.124 | 0.130 | 0.134 |
| E | 3.15 | 3.30 | 3.40 | 0.124 | 0.130 | 0.134 |
| E2 | 2.15 | 2.25 | 2.35 | 0.085 | 0.089 | 0.093 |
| L | 0.35 | 0.40 | 0.45 | 0.014 | 0.016 | 0.018 |
| N | 2.10 | 2.25 | 2.35 | 0.083 | 0.089 | 0.093 |
| e | -- | 0.65 | -- | -- | 0.026 | -- |